

SiC Road Map

~Future Society based on Power Electronics~

16th Dec., 2020

SiC alliance Planning Committee



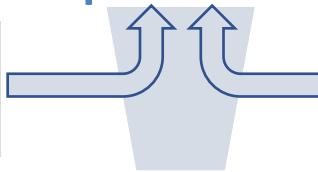
1. Vision

Revised : 20th Oct. 2016

Realize the Ultimate Eco-Society

Create Competitive Companies and Brand-new Markets

Promote Electric Powertrains
for Mobility of Ground, Sea, Sky



Establish Energy Networks
Maximize Renewable Energy



Source: JR East

Commercialized in 2015

Revolution of System Design

SiC Characteristics make
System Design new



Eco-Friendly
with New Function
or New System



Maximize Renewable Energy



Source: Toyota Motor corp.

Commercialize around 2020

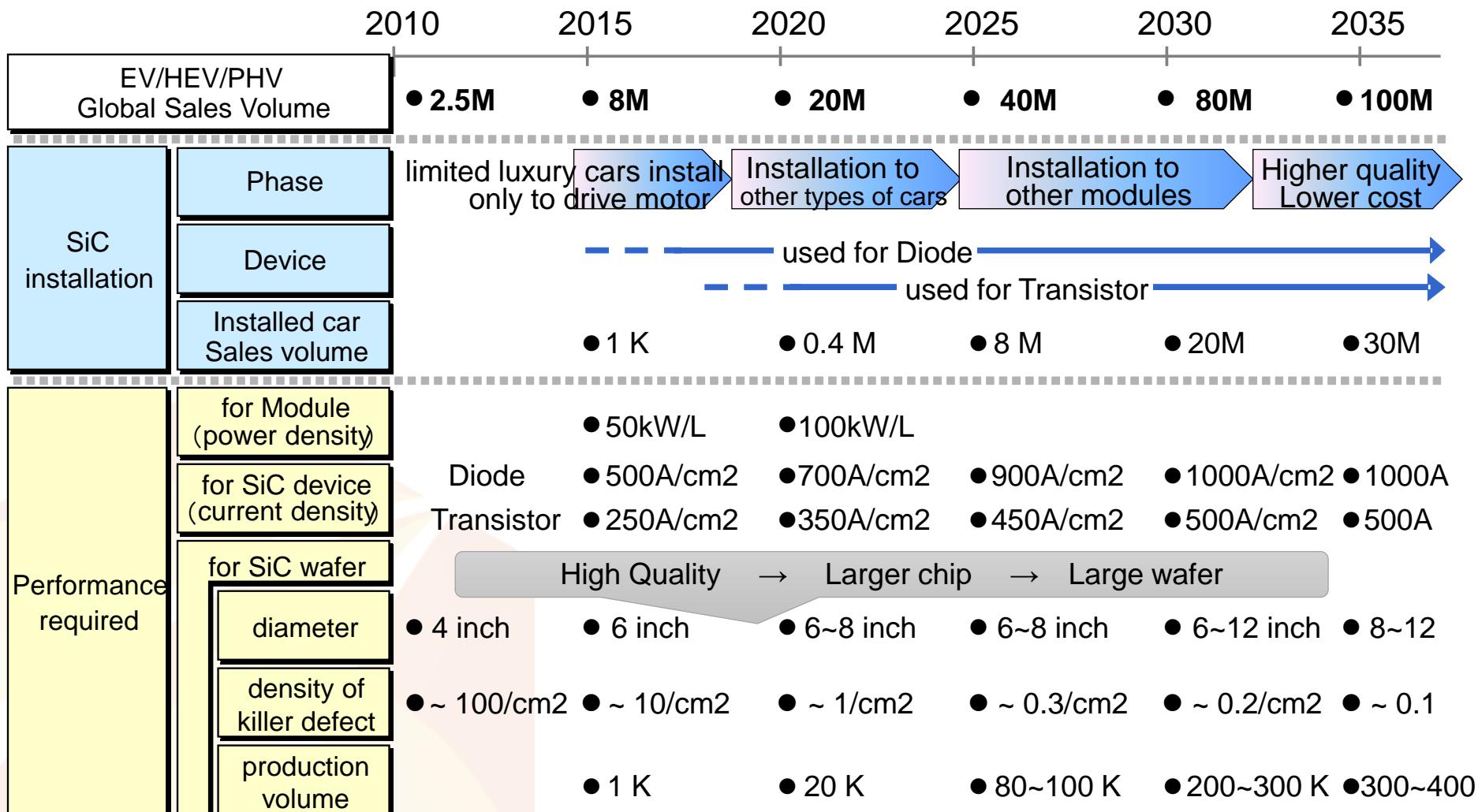


Source: Toyota Motor corp.



2. Auto Mobile

Revised : 7th Oct. 2020



Source: Yole Developpement "Power GaN"; Fuji Economist Research "Market Perspective of Next Generation Power Devices2011"; DI interviews and analysis (estimated in 2011)

3. Super Express Train

Revised : 20th Oct. 2016

		2010	2015	2020	2025	
Social situation	Global	210B\$ Bullet trains: China, Spain, France, Russia, India, USA Conv.: Europe (Replacement), Developing Countries (City)	250B\$ Next Generation Bullet Train 400km/h (DLR, Germany)	● Beijing-Moscow 400km/h	● Future : Evacuated Tube Transport (6500km/h) Hyperloop (1200km/h) Packet Transport	
	Japan	Conv.: Replacement (depopulation)	● Bullet train (Tokyo-Hokkaido) (1st section)	● Bullet train (Kanazawa-Osaka) (2nd section)	● Maglev (Tokyo-Nagoya) *Maglev: Magnetic levitation (500km/h)	
System	High-speed railway	weight reduction energy saving			Bullet train (SiC Diode & MOSFET)	
	Vehicle	as above	Subway (SiC Diode)	Conventional Line (SiC MOSFET)	Solid State Transformer (for 16.7Hz, 50/60Hz, power grid)	
	Power supply	space reduction energy saving		Station Auxiliary Power Supply Unit, Railway Substation		Maglev
Components	Motor	Induction Motor	Synchronous Motor	Reluctance Motor		
	Battery		Vehicle & Ground: reuse of EV battery (low cost, high reliability, compact)			
	Inverter Converter		Traction converter unit: high efficiency inverter, Matrix converter, high-frequency insulation transformer Auxiliary power supply: volume reduction by high frequency operation, contactless feeding, low EMI Ground power supply: Rectifier, regenerating inverter, DC circuit breaker, reactive power compensator, power storage			
	Module		higher voltage/frequency/temperature, cooling technology, lower cost, monitoring technology			
	SiC Power device	1.7kV	3.3kV	6.5kV	13kV	26kV

*Based on commercial operation



Take off to the world with new generation power electronics

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4. Industrial Inverter

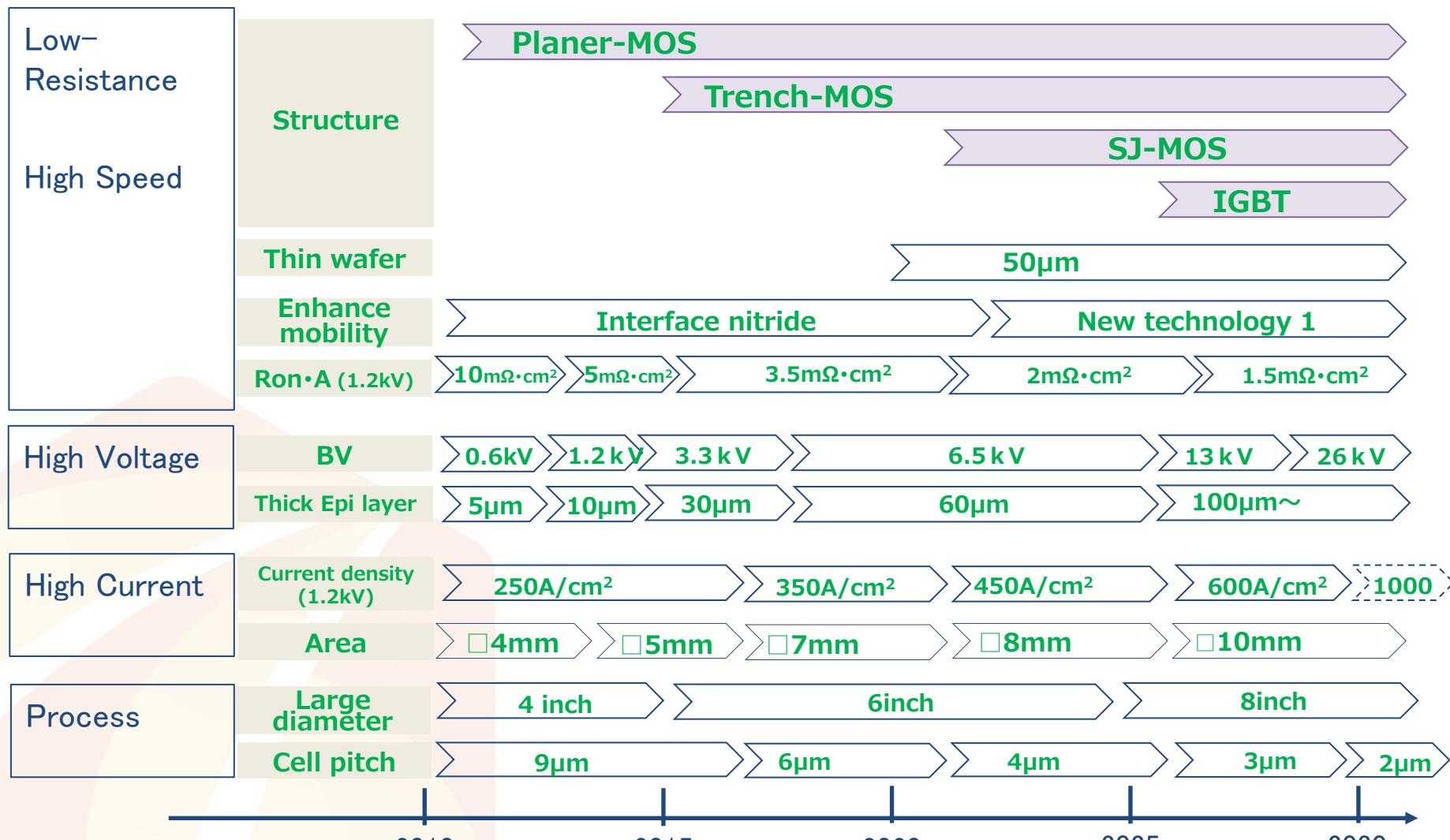
Revised :5th Feb. 2018

		2010	2015	2020	2025			
1.2kV Device (MOS)	Spec.	R_{onA}	$5.0 \text{ m}\Omega\text{cm}^2$	$3.5 \text{ m}\Omega\text{cm}^2$	$2.0 \text{ m}\Omega\text{cm}^2$	$1.5 \text{ m}\Omega\text{cm}^2$	$1.0 \text{ m}\Omega\text{cm}^2$	$0.75 \text{ m}\Omega\text{cm}^2$
	$E_{on} + E_{off}$		$\bullet 35 \mu\text{J}/\text{pulse} \cdot \text{A}$ (@ $V_{bus}=800\text{V}$)			$\bullet 25 \mu\text{J}/\text{pulse} \cdot \text{A}$ (@ $V_{bus}=800\text{V}$)		
System				Inverter with Motor (Industrial)				
HV Device (MOS/ IGBT)	Spec.	BV	1.2kV	3.3kV	6.5kV	1.2kV $2.0\text{m}\Omega\text{cm}^2$	13kV	26kV
	System			Modular Multilevel Converter				

Source: Fuji Electric, Nikkei, SIP

5. Switching Device

Revised: 9th Sep. 2020



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Passive Component Road Map

Updated on Dec. 16, 2020

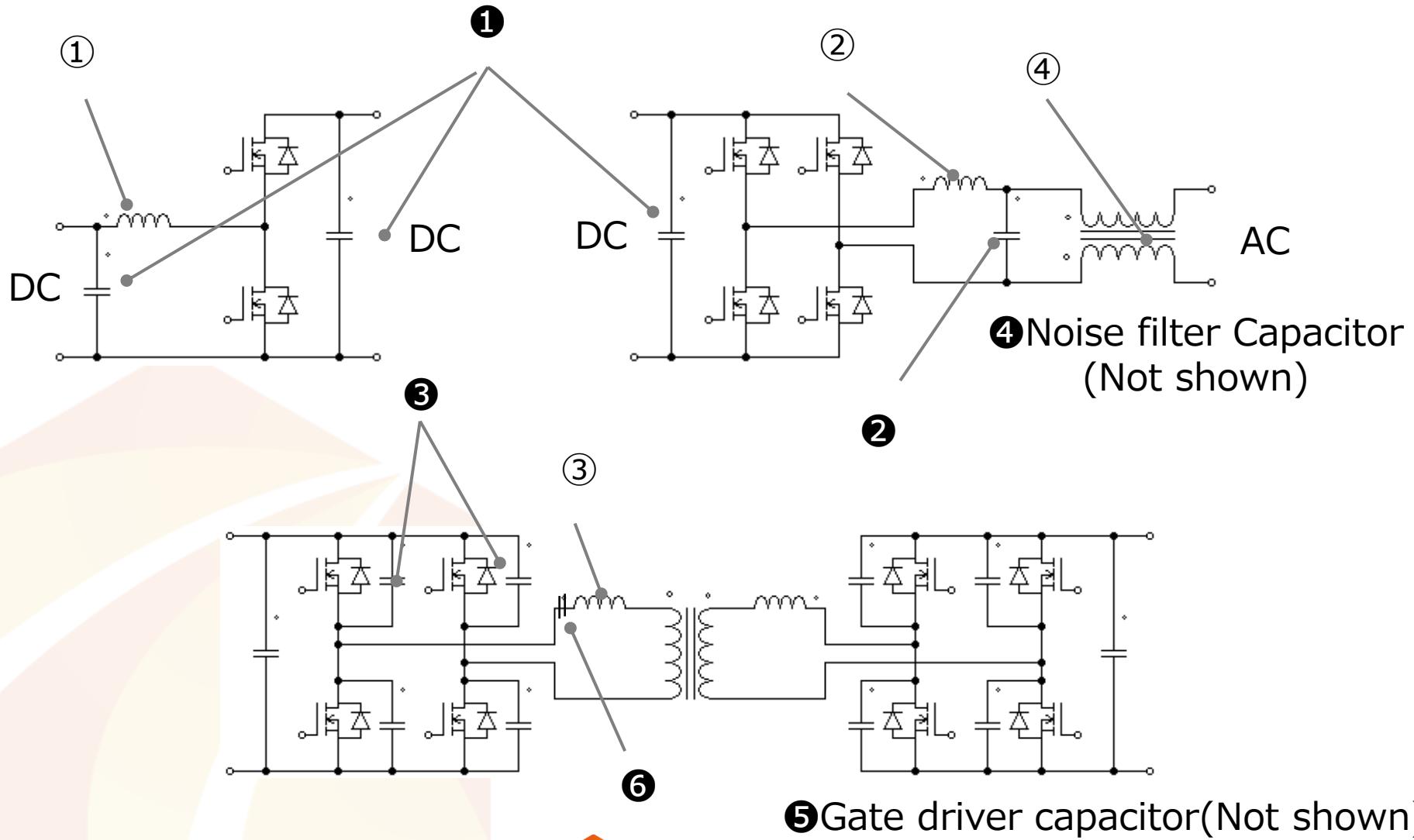
		CY2020	CY2030年	CY2035
Inductor	①	Frequency adaptation	50kHz	100> 200
	②		Non-disclosure	
	③	Operating temperature	125°C	150>
	④	Permeability	1	1.2> 1.3
Ceramic	①		Non-disclosure	
	②			
	③	Capacity density	1	1.5 2.0>
	④		Non-disclosure	
Capacitor	⑤	Breakdown voltage	1	1.5 2.0> 2.5
	⑥	Operating temperature	150°C	175 200> 250
	①②⑤			
	①②			
Film	③		Non-disclosure	
	④			
	⑤	Capacity density	1	1.2> 1.3
	⑥		Non-disclosure	
	①	Breakdown voltage	1	>
	②	Operating temperature	105°C	125 > 150
			Non-disclosure	



SiC Alliance

次世代パワー半導体の滑走路で、世界へ向けてテークオフ

Inductor and Capacitor for Power



7. Wafer

Revised: 9th Sep. 2020

